Paramètres des tests :

test6 : Clean contact

Dose EBL : 1000 -> 3000 µc/cm² [500]

20s MIBK / 20s MG / IPA

Plasma 2 min / Pression = 4.10-4mbar / I\_power = 35mA / V = -0.4kV / Ion energy = 1 kV

20nm Al 14°

25nm Cu -14°

Acetone

test7 : NIS

Dose EBL : 1000 -> 3000 µc/cm² [500]

20s MIBK / 20s MG / IPA

Plasma 2 min / Pression = 4.10-4mbar / I\_power = 35mA / V = -0.4kV / Ion energy = 1 kV

20nm Al 14°

Ox 1mbar / 1 min

25nm Cu -14°

Acetone

test8 :

Dose EBL : 1000 -> 3000 µc/cm² [500]

20s MIBK / 20s MG / IPA

Plasma 2 min / Pression = 4.10-4mbar / I\_power = 35mA / V = -0.4kV / Ion energy = 1 kV

20nm Al 14°

25nm Cu -14°

Acetone

test9 :

Dose EBL : 1000 -> 3000 µc/cm² [500]

20s MIBK / 20s MG / IPA

20nm Al 15°

Ox 10min / 0.2 bar

Plasma 25 min / Pression = 4.10-4mbar / I\_power = 40mA / V = -0.8kV / Ion energy = 1.5 kV

25nm Cu -15°

Acetone

test10 : Raté à cause de problème EBL : tentative de changement de pattern

test11 : Raté à cause de problème EBL (vérification)

test12 : Clean contact de référence :

Pattern 4 pads

Dose EBL : 2000 -> 3000 µc/cm² [250]

Surface de jonction : 2µm² -> 0.5µm²

20s MIBK/20s MG/IPA

Plasma 2 min / 4.10-4mbar / 35mA / -0.4kV / 1 kV

20nm Al 15°

25nm Cu -15°

Acetone

test13.i : i = position dans évaporateur (Centre/bas/haut/droite = 2/1/3/4)

Pattern 4 pads

Dose EBL : 2000 -> 3000 µc/cm² [250]

Surface de jonction : 2µm² -> 0.5µm²

20s MIBK / 20s MG / IPA

20nm Al 15°

Ox 10min / 0.2 bar

Plasma 10 min / Pression = 4.10-4mbar / I\_power = 40mA / V = -0.8kV / Ion energy = 1.5 kV

25nm Cu -15°

Acetone